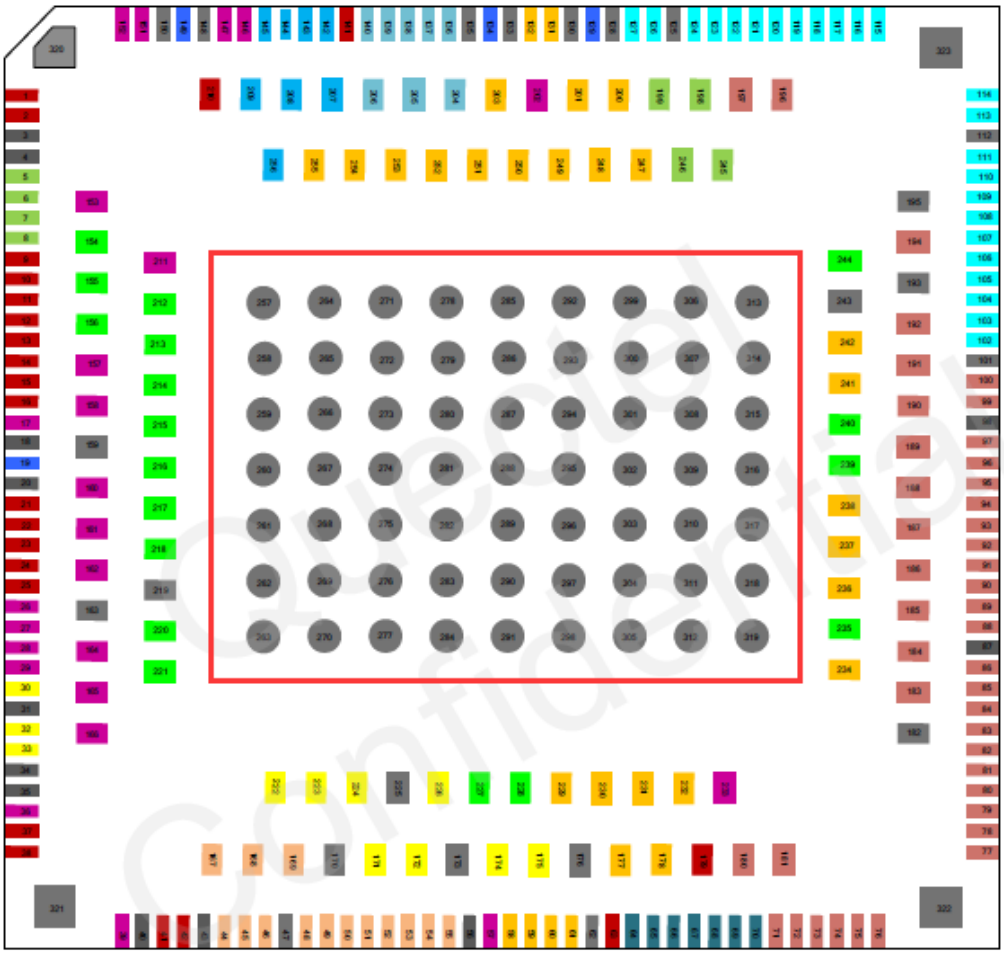
1st it is recommended to add some heat spreading and TIM for heat dissipation on SC60 shielding cover.
2nd SC60 cover does not touch snapdragon chipset. And because it need second reflow, so it is impossible to add TIM between snapdragon chipset and SC60 shielding cover.
If possible, customer can remove the shielding cover and add the thermal interface material between chipset and shielding cover and reassemble the shielding cover.
By the way ,the space between shielding cover and snapdragon is about 0.4 millimeter.

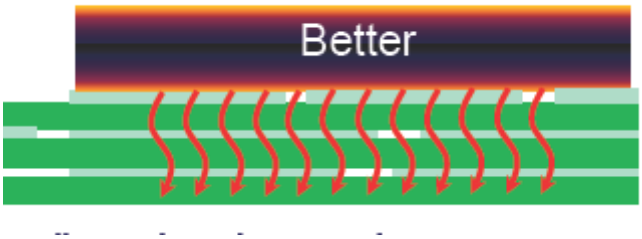
And The following is some information about power consumption of SC60. Customer can refer to them to do some heat dissipation design.

And there are some suggestions about thermal design as below.

1. Connect the GND and Heat dissipation pads to the application board well. And add enough vias under or near the SC60 module to the bottom of the application board for better heat dissipation.



2. Increase the conductivity of PCB with added layers and copper on each layer to provide a low resistance cooling path.



3. Avoid high power density parts side by side or front-to-back from SC60 module. Keep heat generating item far away from SC60 such as audio PA, Battery, LCD, Camera, DCDC and so on.
4. Take some advantage of the mechanical structure of the design. Such increase board size when possible, use metal frame as a heat sink, Minimize gaps in the stack-up and so on.
5. Use TIM and Heat spreading for heat dissipation.(Even customer can use head sink for head dissipation, but must to check the reliability of structure.

6. It is recommended to add Heat sink to increase heat dissipation area. The following figures are two kinds of heatsink designs for reference and customers can choose one or both of them according to their application structure.

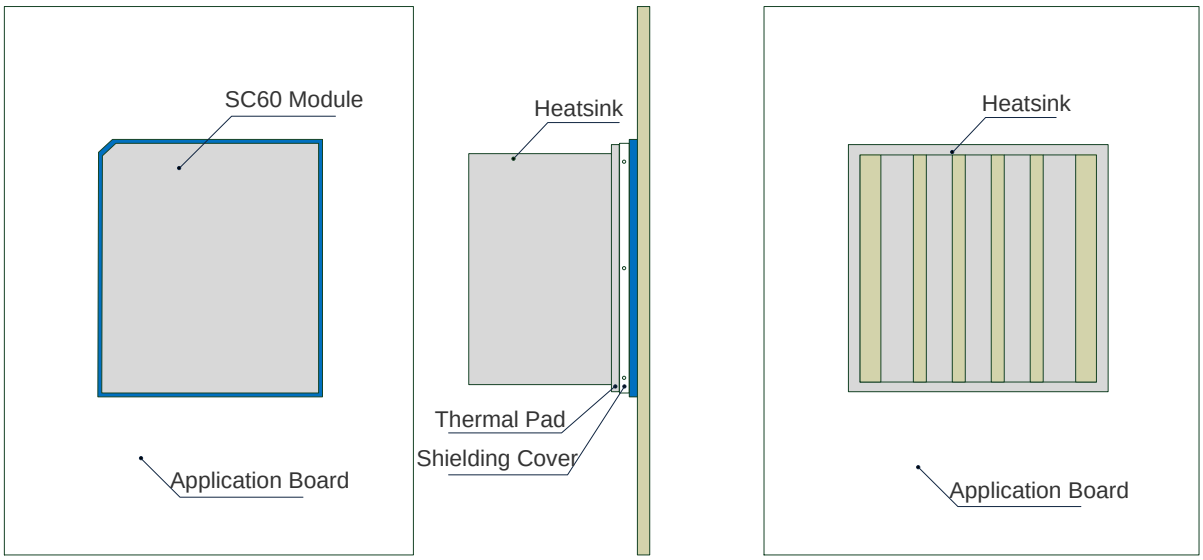


Figure 1: Referenced Heatsink Design (Heatsink at the Top of the Module)

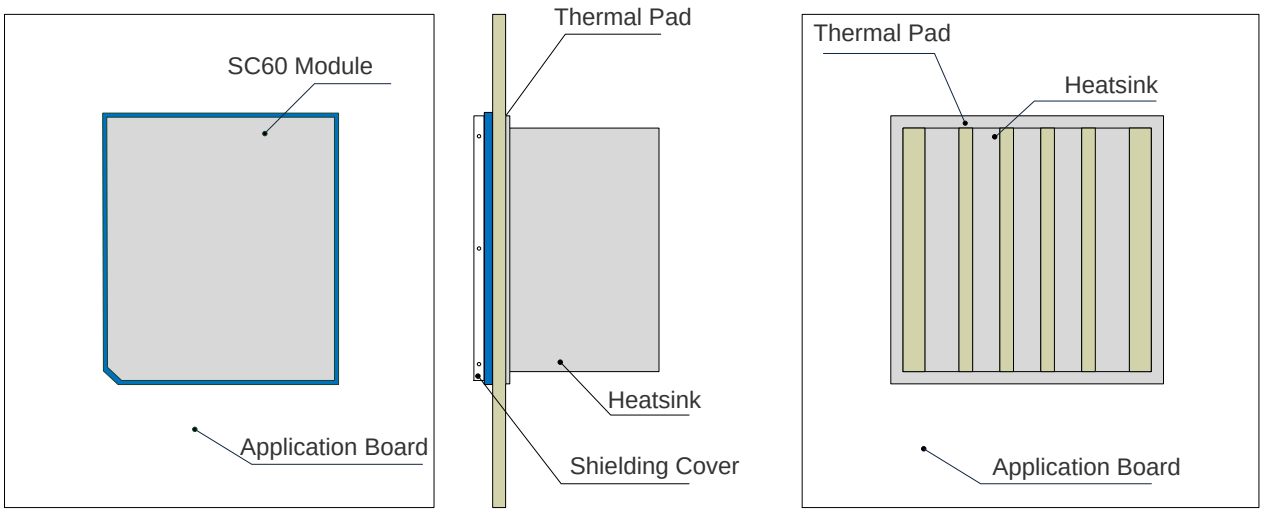


Figure 2: Referenced Heatsink Design (Heatsink at the Backside of Customers' PCB)